

### Discription

The ESD8D12C protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD. It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.

# **Features**

★ Small Body Outline Dimensions:

1.00 mm x 0.60 mm

- ★ Low Body Height: 0.50 mm
- ★ Low Leakage
- ★ Response Time is Typically < 1 ns
- ★ ESD Rating of Class 3 per Human Body Model
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ We declare that the material of product compliance with RoHS requirements and Halogen Free.

## **Ordering information**



DFN1006-2L (SOD-882)



**Circuit Diagram** 

Product ID	Pack	Qty(PCS)	
ESD8D12C	DFN1006-2L(SOD-882)	10000	

## Absolute Ratings (T<sub>amb</sub>=25°C)

Symbol	Parameter	Value	Units
P <sub>PP</sub>	Peak Pulse Power ( $t_p = 8/20 \ \mu \ s$ )	140	W
TL	Maximum lead temperature for soldering during 10s	260	°C
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C
T <sub>op</sub>	Operating Temperature Range	-55 to +150	°C
Tj	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	土20 土20	KV



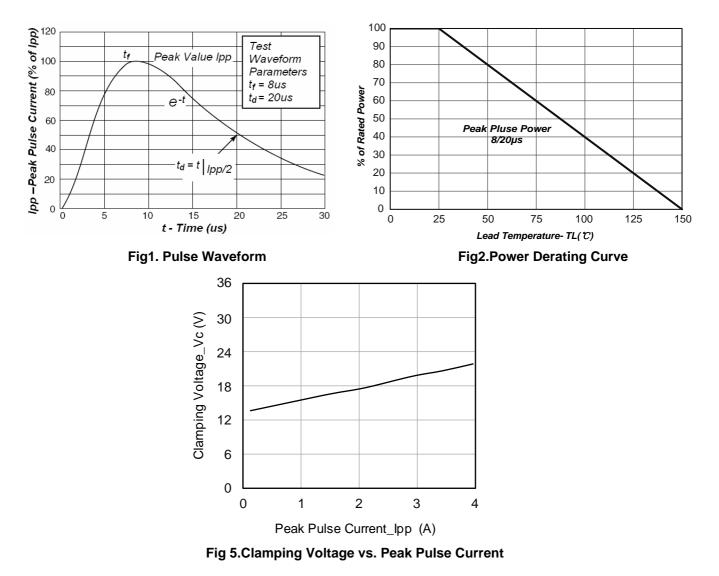
# **Electrical Characteristics**

	V <sub>RWM</sub> (V)	I <sub>R</sub> (μΑ) @ V <sub>RWM</sub>	V <sub>BR</sub> (V) @ I <sub>T</sub>		Ι <sub>Τ</sub>	V <sub>C</sub> (V) @ I <sub>PP</sub> =8A	I <sub>PP</sub> (A)	P <sub>PK</sub> (W)	C (pF)
Device	Мах	Max	Min	Max	mA	Max	Max	Max	Тур.
ESD8D12C	12	1	13.3	16	1.0	17	8	100	8

1.  $V_{BR}$  is measured with a pulse test current  $I_T$  at an ambient temperature of 25  $^\circ\!\!\mathbb{C}$ .

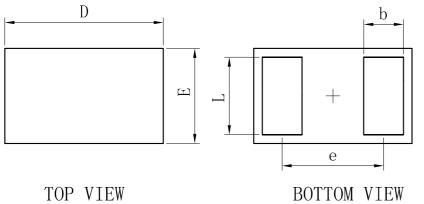
2. Surge current waveform per Figure 1.

# **Typical Performance Characteristics (T<sub>A</sub>=25°C unless otherwise Specified)**

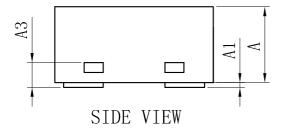




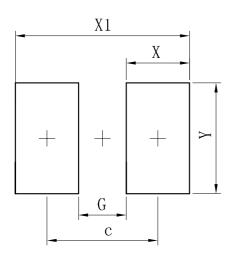
#### **OUTLINE AND DIMENSIONS**



DFN1006-2L(SOD-882)						
Dim	Min	Min Typ				
D	0.95	1.00	1.05			
Е	0.55	0.60	0.65			
е	-	0.64	-			
L	0.44	0.49	0.54			
b	0.20	0.25	0.30			
А	0.43	0.48	0.53			
A1	0 – 0.05					
A3	0.127REF.					
All Dimensions in mm						



#### SOLDERING FOOTPRINT



Dimensions	(mm)
С	0.70
G	0.30
Х	0.40
X1	1.10
Y	0.70



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